


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MICROCONTROLLERS/24/14725	
1.3 Title of PCN	STM32H7Rxx and STM32H7Sxx - product enhancement and BOM optimization	
1.4 Product Category	STM32H7R3xx, STM32H7R7xx, STM32H7S3xx, STM32H7S7xx	
1.5 Issue date	2024-10-29	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign: Mask or mask set change with new die design - Design changes in active elements.	ST Crolles 300 (France)

4. Description of change

	Old	New
4.1 Description	<p>STM32H7x - (Die485 – cut1.2 revision Y) product enhancement shows some limitations</p> <p>Errata Sheet : ES0596 rev 4 July 2024) describes the limitations</p> <p>Datasheets : DS14359 rev2 (crypto) & DS14360 rev 2 (non crypto) are impacted</p> <p>Assembly : Gold wire Bonding wire material</p>	<p>STM32H7x - (Die485 - cut2.0 revision B) product enhancement as below</p> <p>Errata Sheet new release : ES0596 rev5 october 2024 fixes those limitations.</p> <p>Datasheets new releases : DS14359 rev3 (crypto) & DS14360 rev3 (non crypto) are updated.</p> <p>Assembly : Copper Palladium Bonding wire material.</p>
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Functionality enhancement	

5. Reason / motivation for change

5.1 Motivation	Improvements was implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "Y" to "B" on Package Marking.
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7. Timing / schedule

7.1 Date of qualification results	2024-09-10
7.2 Intended start of delivery	2025-01-24
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
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8.1 Description	14725 MDG-GPM-RER2202_PCN14725 -STM32H7Rxx-DIE485 Reliability Evaluation Report_V2.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2024-10-29

9. Attachments (additional documentations)			
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14725 Public product.pdf
 14725 MDG-GPM-RER2202_PCN14725 -STM32H7Rxx-DIE485 Reliability Evaluation Report_V2.pdf
 14725 PCN14725_Additional information.pdf

10. Affected parts		
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10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H7R3A8I6	
	STM32H7R3I8K6	
	STM32H7R3I8T6	
	STM32H7R3L8H6	
	STM32H7R3L8H6H	
	STM32H7R3V8T6	
	STM32H7R3Z8J6	
	STM32H7R3Z8T6	
	STM32H7R7A8I6	
	STM32H7R7I8K6	
	STM32H7R7I8T6	
	STM32H7R7L8H6	
	STM32H7R7L8H6H	
	STM32H7R7Z8J6	
	STM32H7S3A8I6	
	STM32H7S3I8K6	
	STM32H7S3I8T6	
	STM32H7S3L8H6H	
	STM32H7S3V8H6	
	STM32H7S3V8T6	
	STM32H7S3Z8J6	
	STM32H7S3Z8T6	
	STM32H7S7A8I6	
	STM32H7S7I8K6	
	STM32H7S7I8T6	
	STM32H7S7L8H6H	
	STM32H7S7Z8J6	

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